

TITLE: METHOD OF ATTACHING SOLDER BALLS TO BGA
PACKAGE UTILIZING A TOOL TO PICK AND PLACE THE SOLDER
BALL IN FLUX

Inventor: Chad A. Cobbley
Serial No.: 09/639,486
Docket No.: 3636.1US (97-1349.1)

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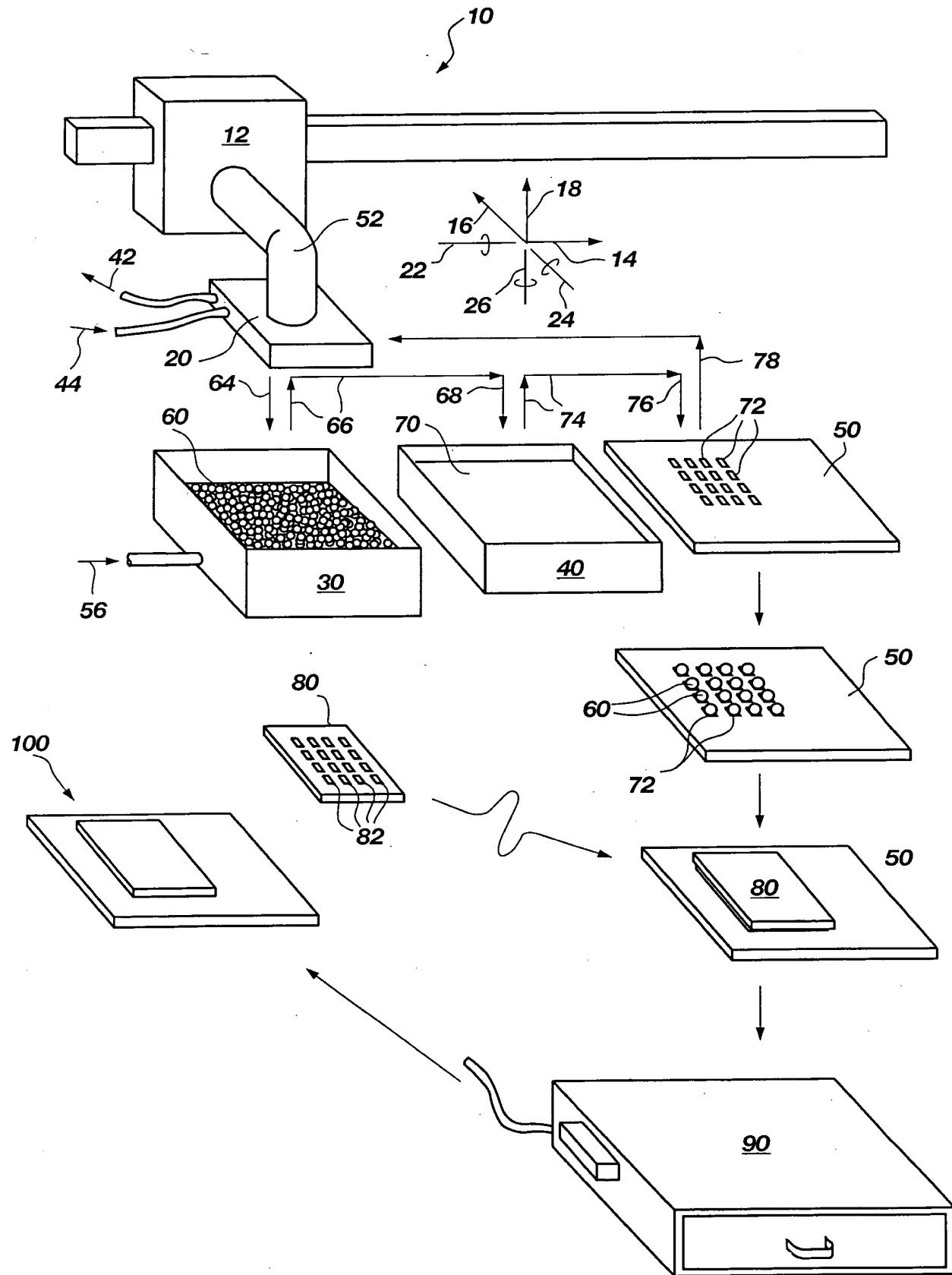
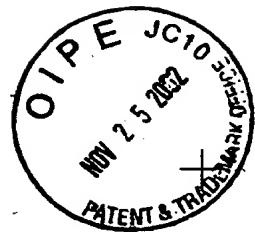


Fig. 1



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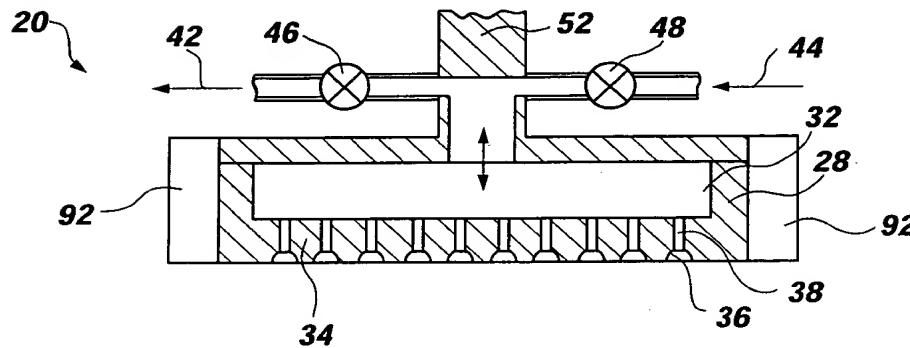


Fig. 2

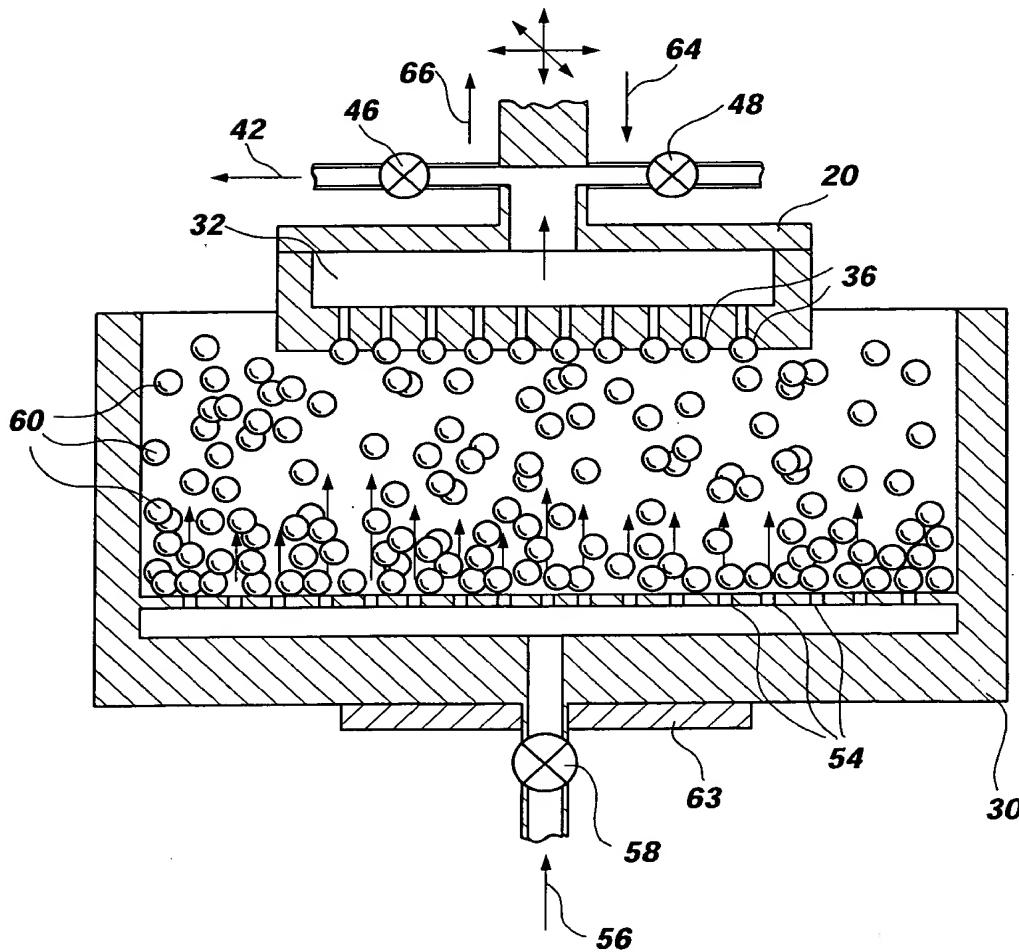
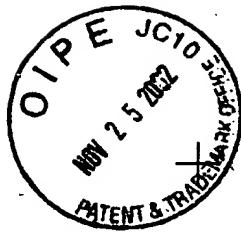


Fig. 3

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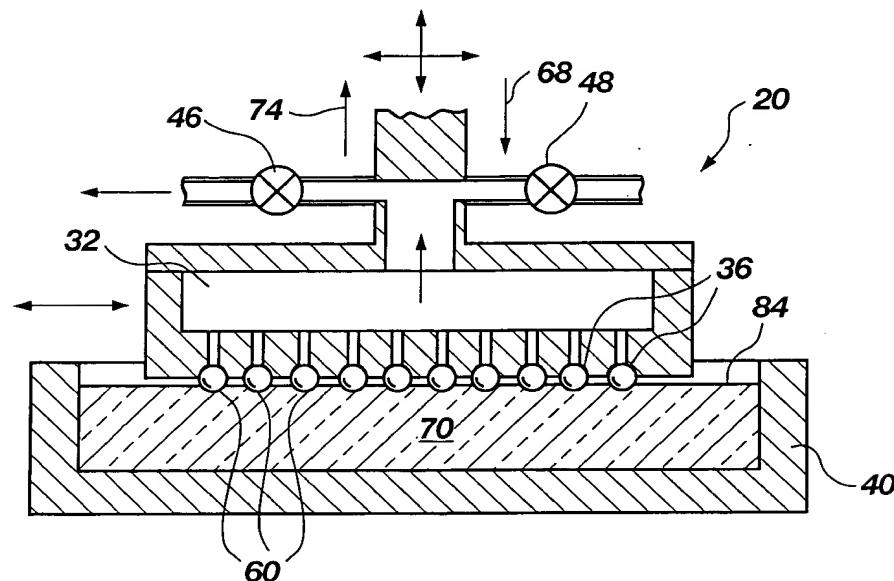


Fig. 4

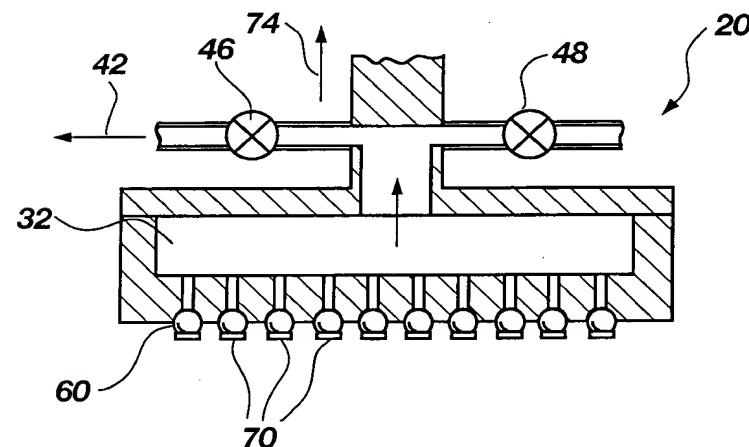


Fig. 5

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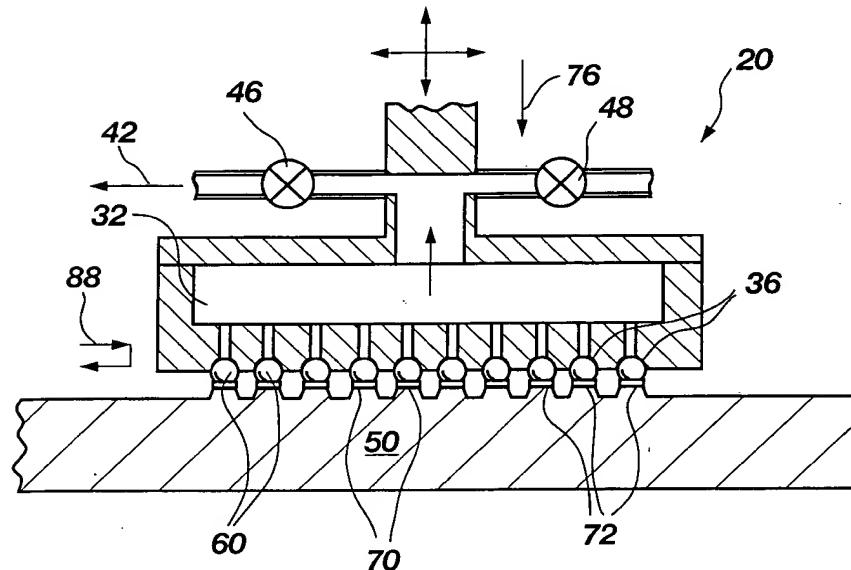


Fig. 6

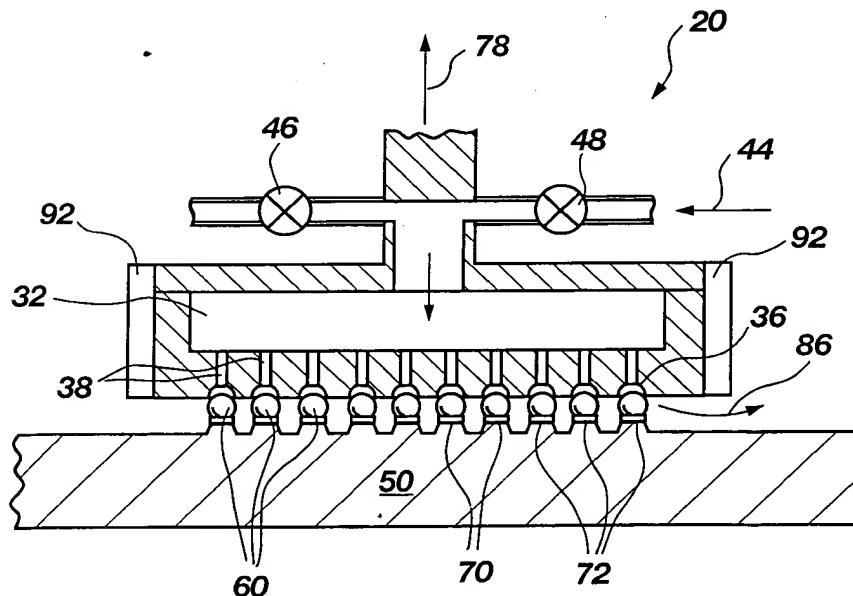


Fig. 7

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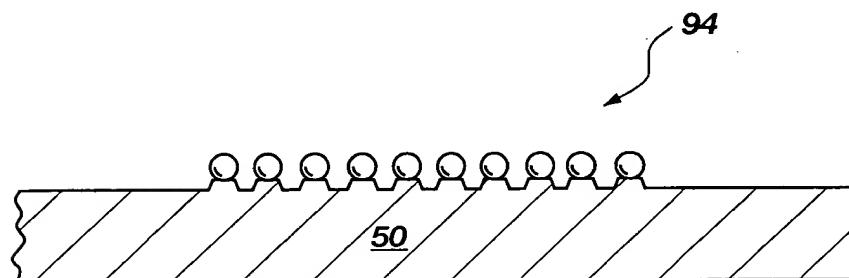


Fig. 8

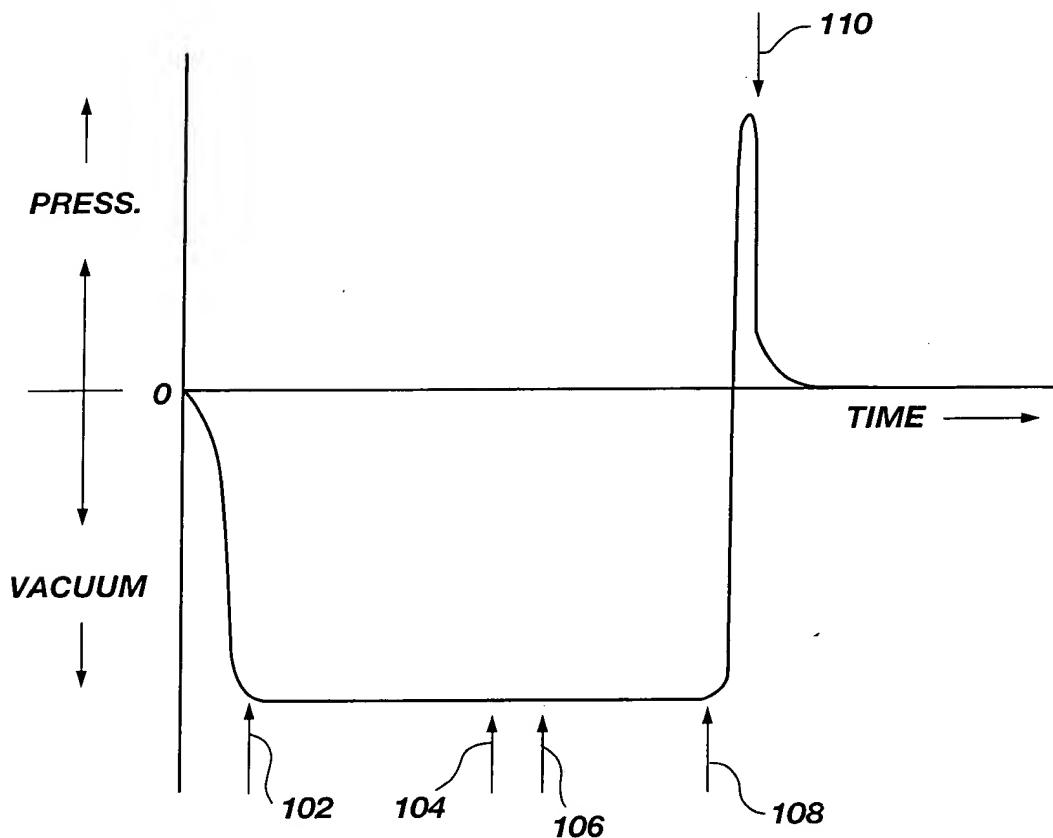


Fig. 9

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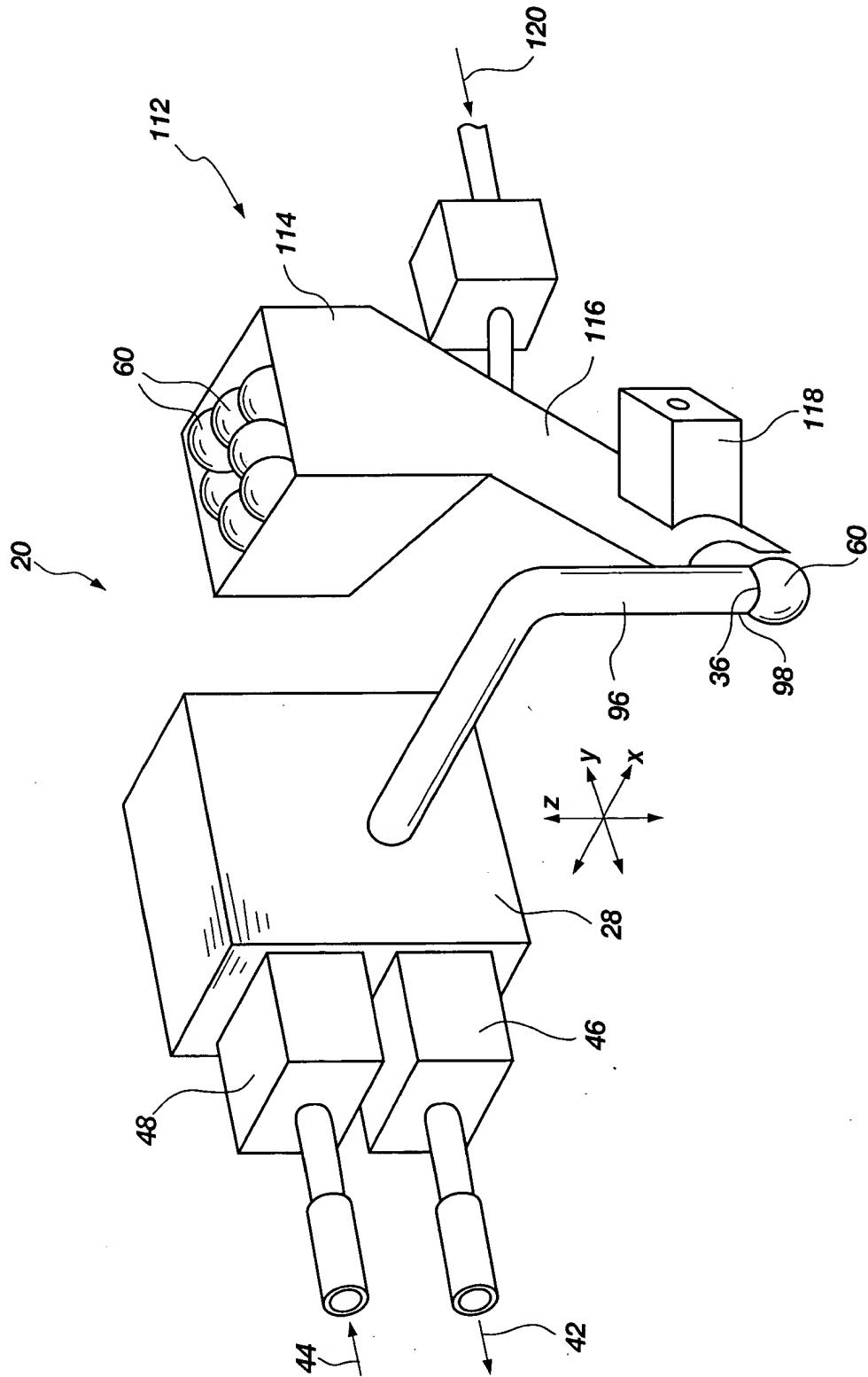


Fig. 10

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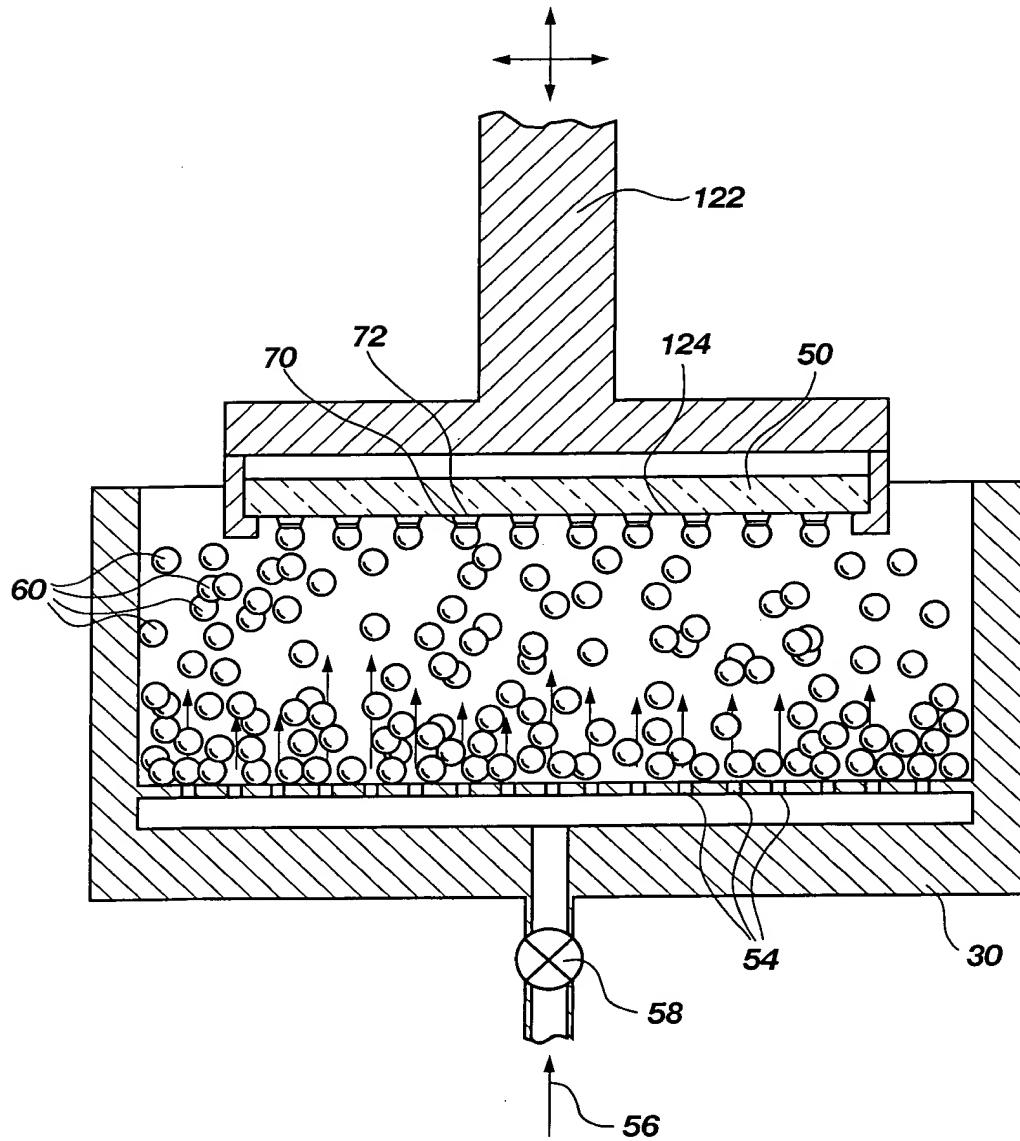
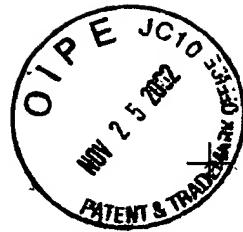


Fig. 11



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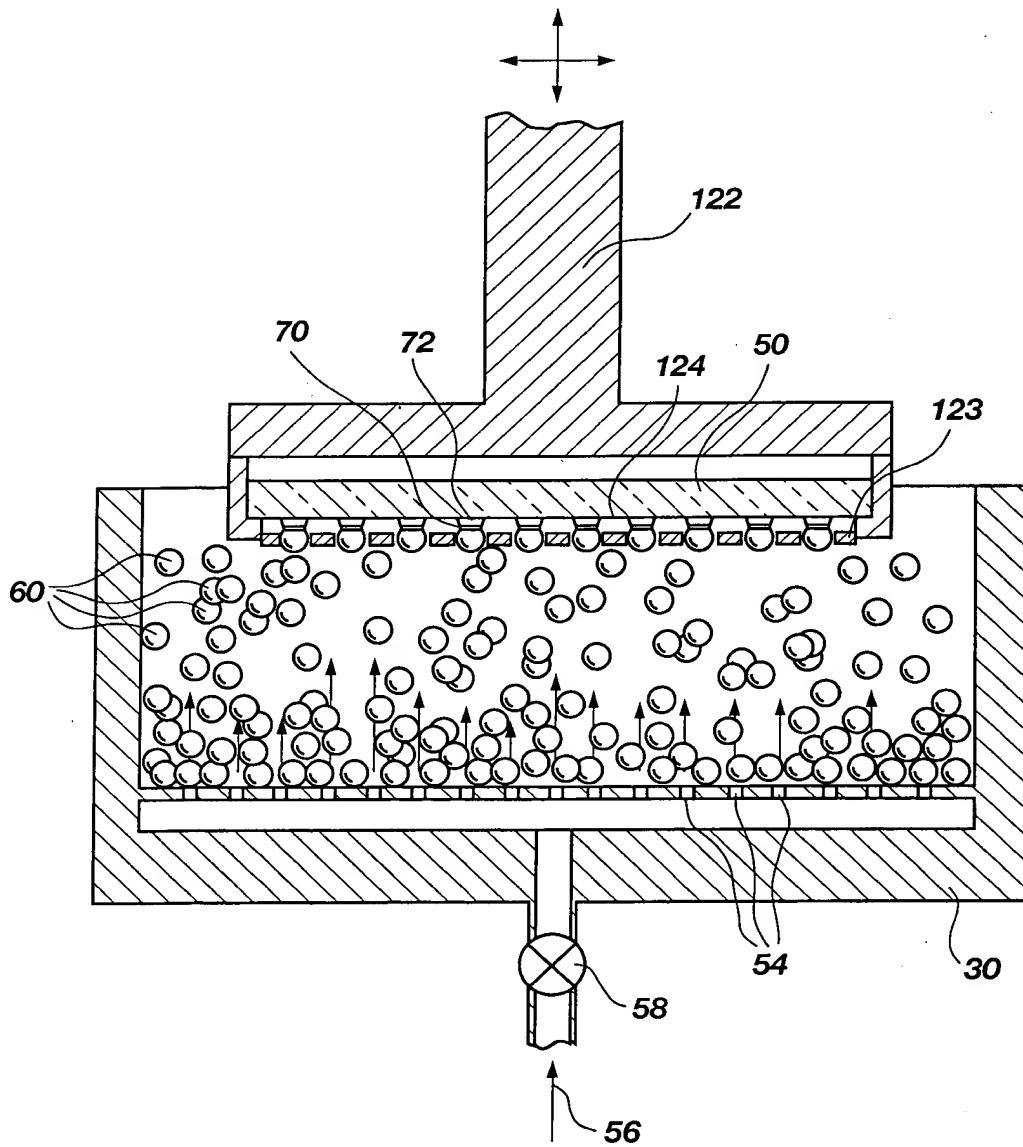
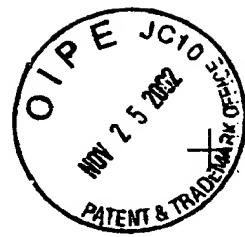


Fig. 11A



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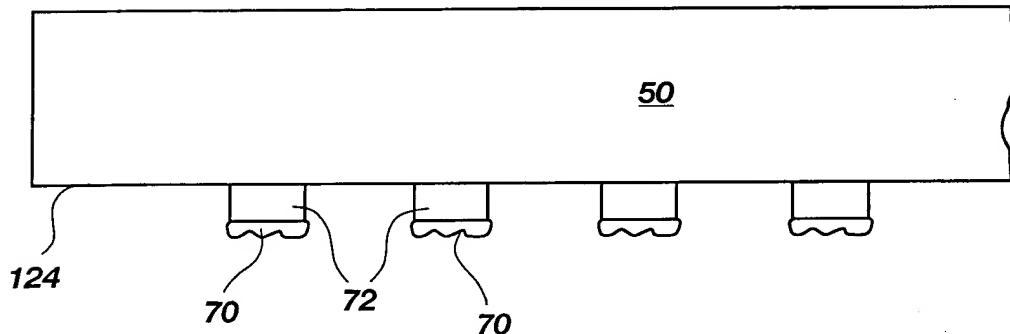


Fig. 12

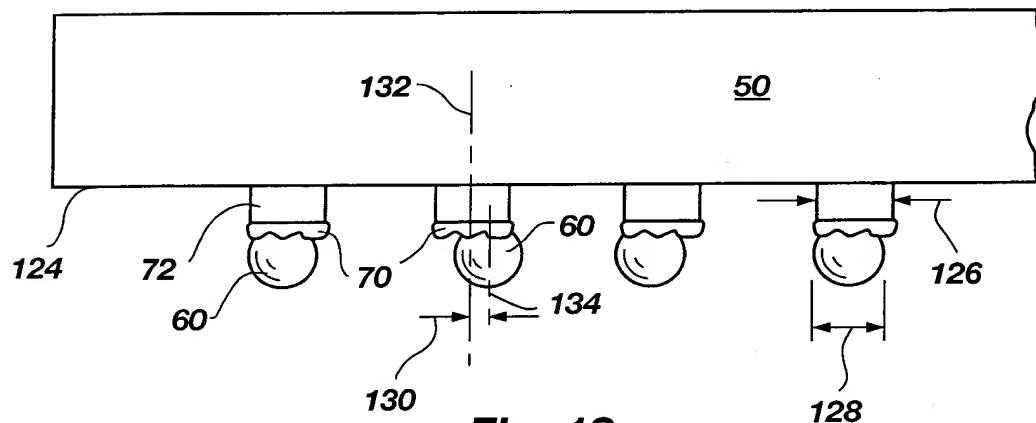


Fig. 13

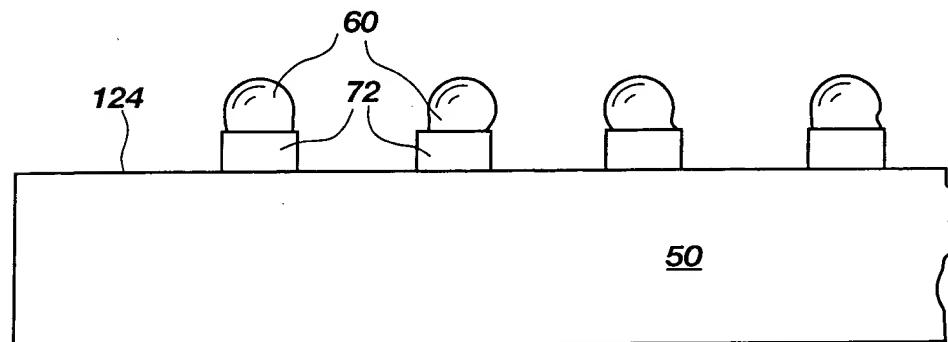


Fig. 14

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